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(12) **United States Design Patent**  
**Soyano et al.**

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(45) **Date of Patent:** **\*\* Dec. 29, 2009**

(54) **SEMICONDUCTOR DEVICE**

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D587,662 S \* 3/2009 Soutome et al. .... D13/182

D589,012 S \* 3/2009 Soyano et al. .... D13/182

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\* cited by examiner

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(\*\*) Term: **14 Years**

(57) **CLAIM**

(21) Appl. No.: **29/327,836**

The ornamental design for semiconductor device, as shown and described.

(22) Filed: **Nov. 14, 2008**

**DESCRIPTION**

(51) **LOC (9) Cl.** ..... **13-03**

FIG. 1 is a perspective view of the front, left and bottom of semiconductor device showing our new design;

(52) **U.S. Cl.** ..... **D13/182**

FIG. 2 is a front view thereof;

(58) **Field of Classification Search** ..... D13/110,  
D13/182; 257/690; 324/754, 755, 765; 361/713,  
361/728, 736, 775

FIG. 3 is a rear view thereof;

FIG. 4 is a left side view thereof;

See application file for complete search history.

FIG. 5 is a right side view thereof;

FIG. 6 is a top plan view thereof; and,

FIG. 7 is a bottom view thereof.

(56) **References Cited**

**U.S. PATENT DOCUMENTS**

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**1 Claim, 5 Drawing Sheets**

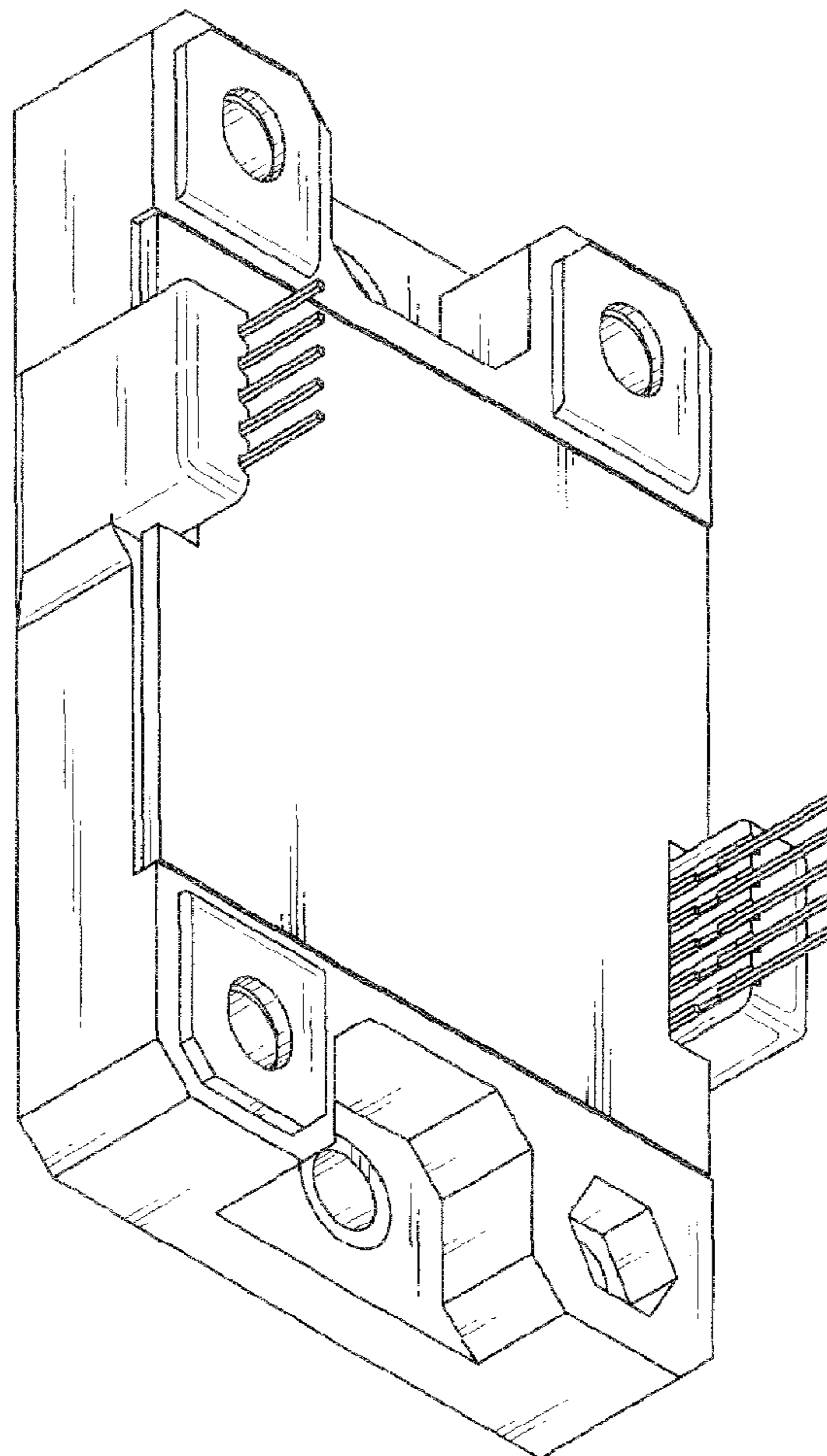


FIG. 1

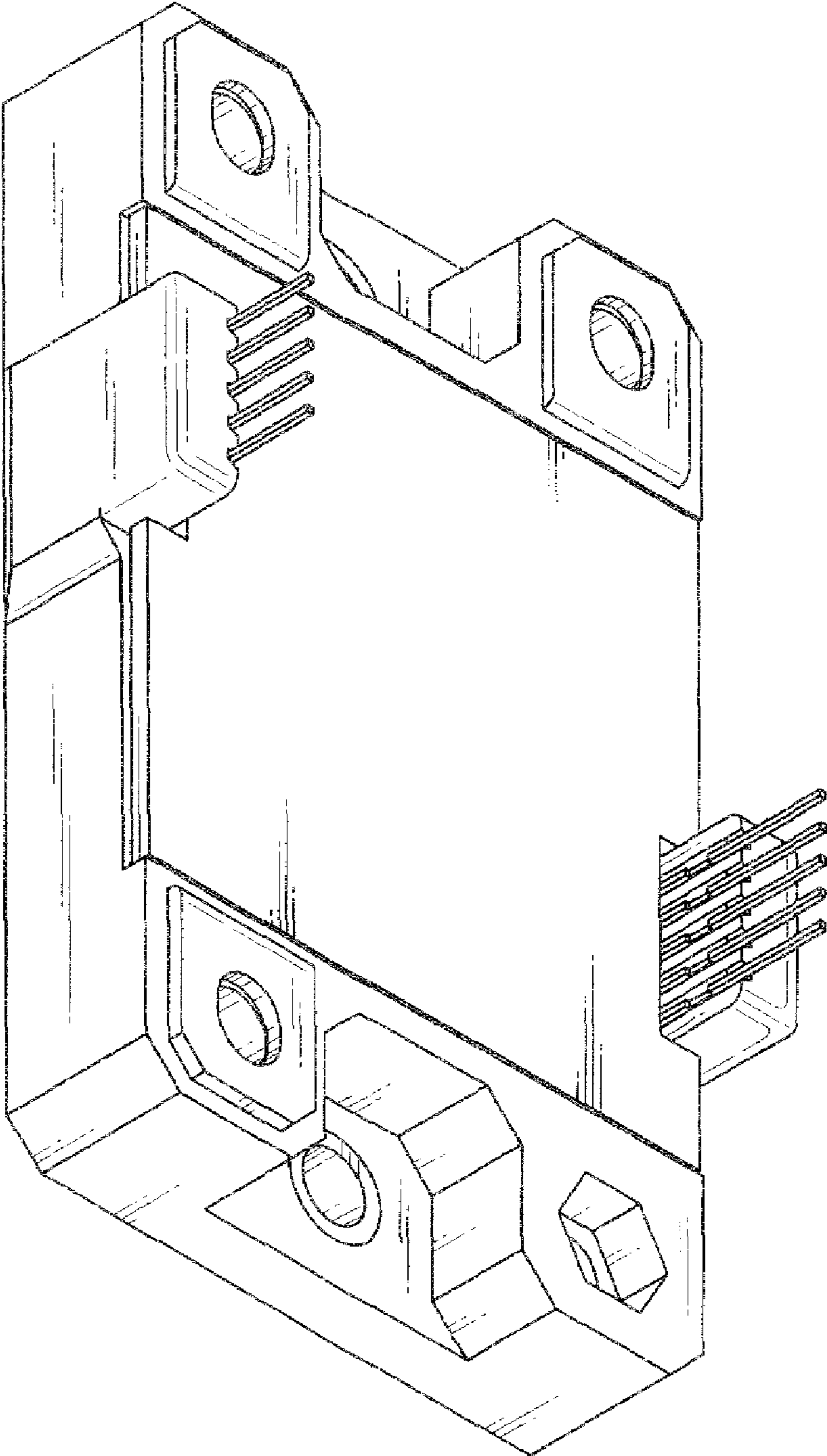


FIG. 2

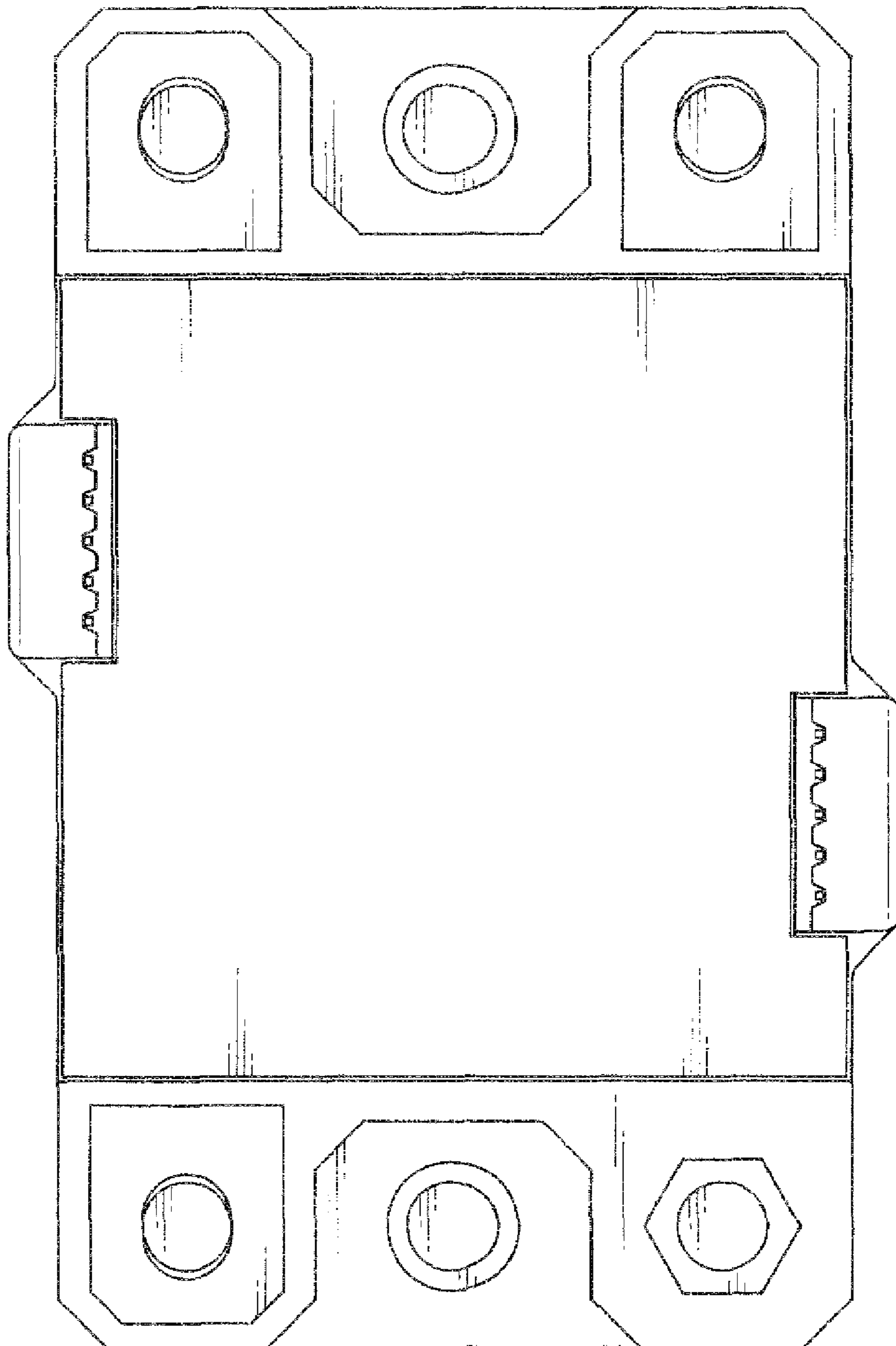


FIG. 3

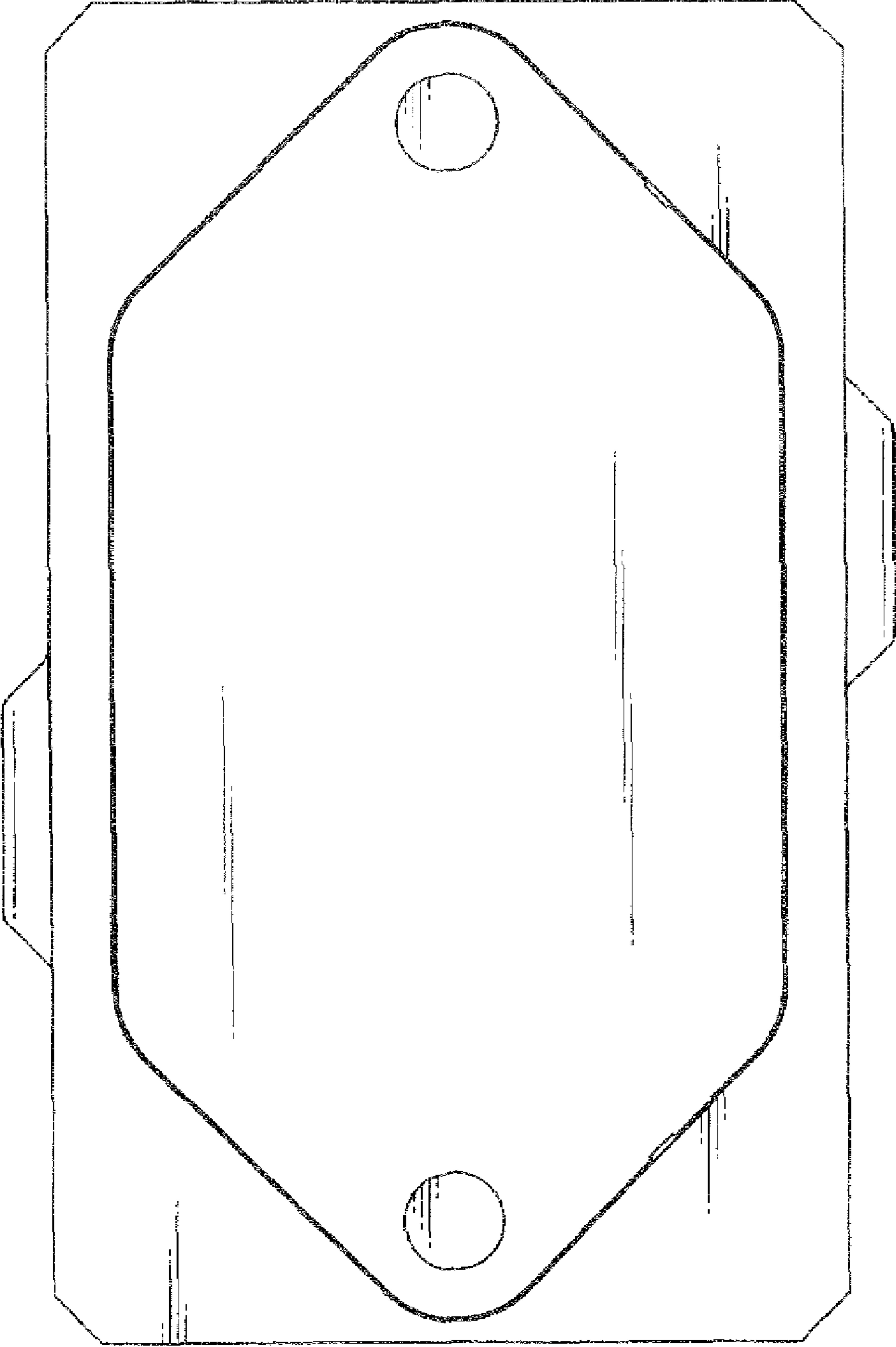


FIG.4

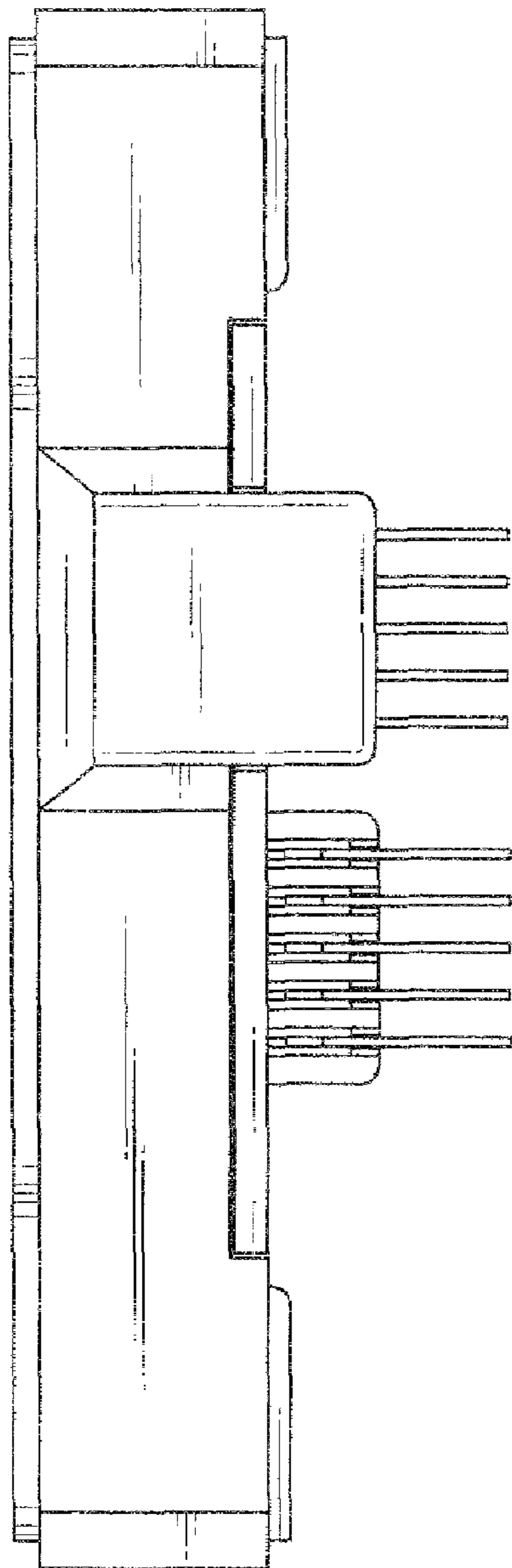


FIG.5

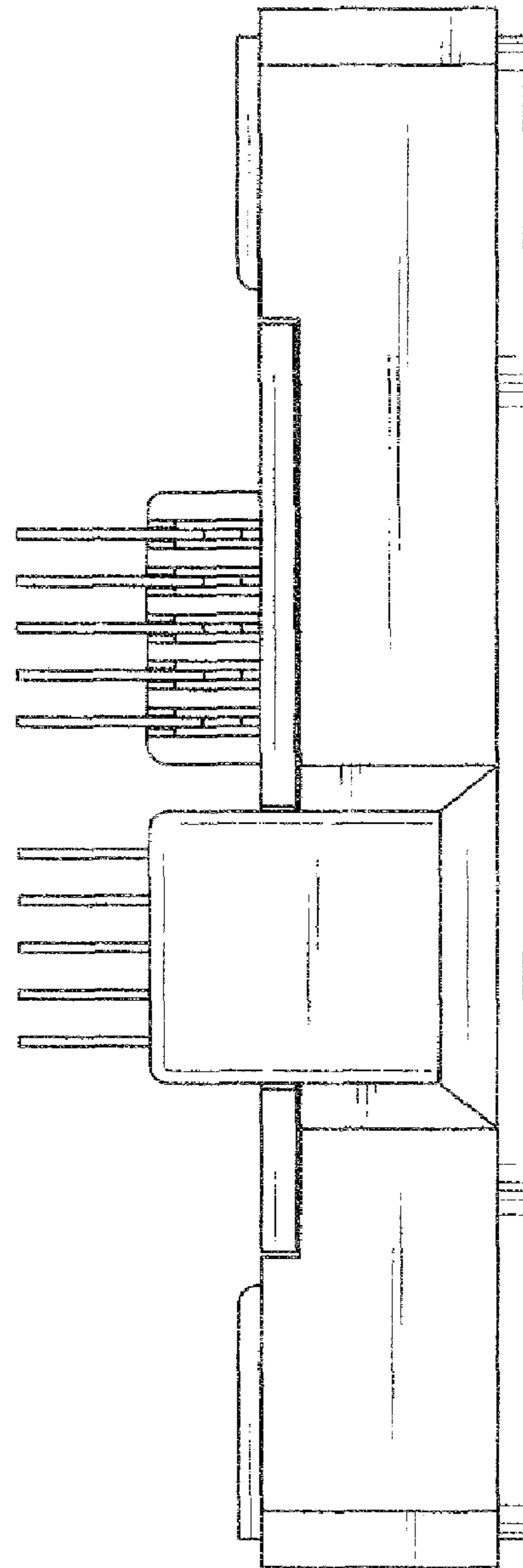




FIG.6

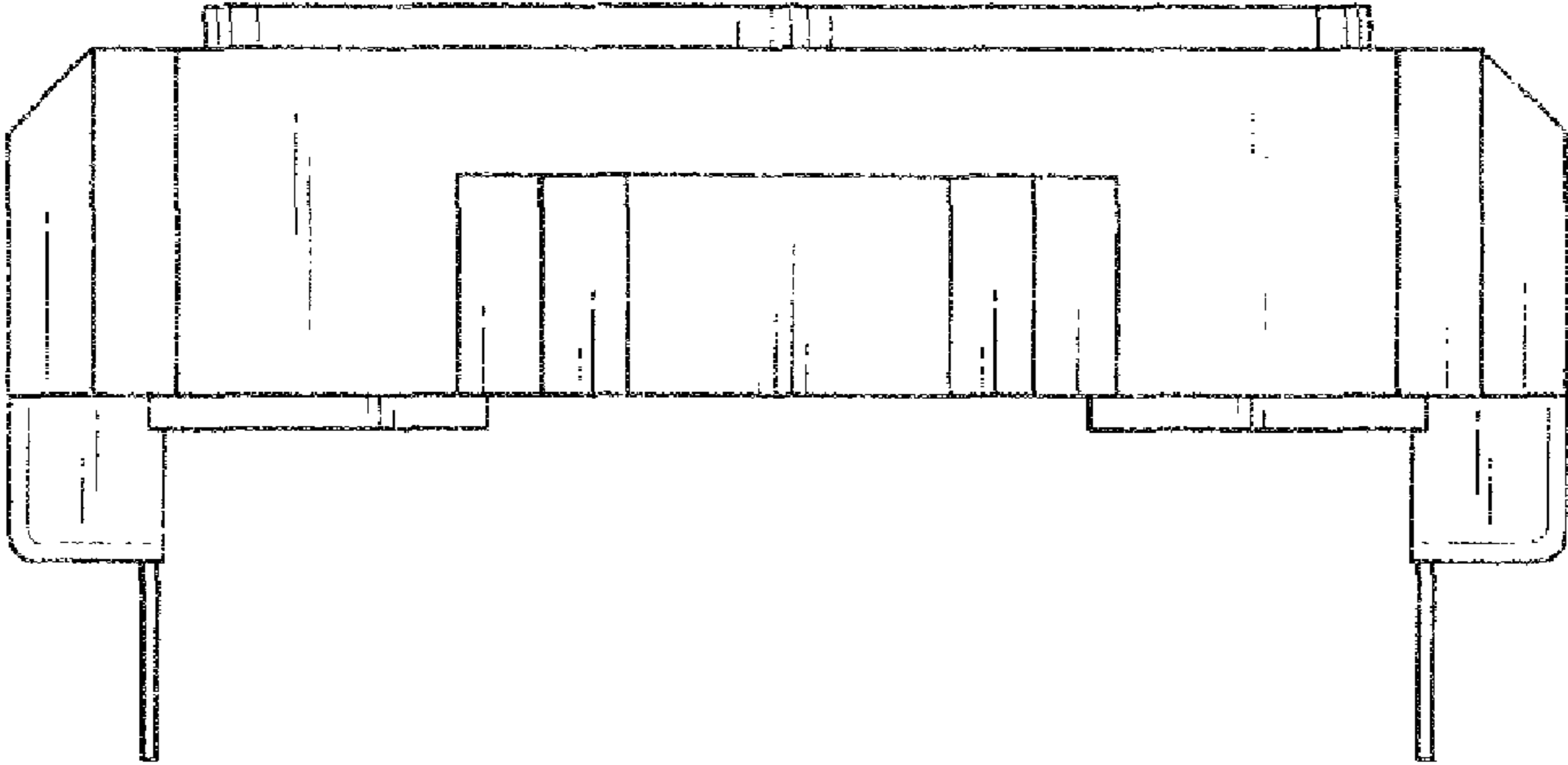


FIG.7

